

MCM16Y1BGCFT16 Information

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General Information

Parameter	Value
Part Number	MCM16Y1BGCFT16
Description	16 BIT MCU, 2K RAM
PTI	JCLB
Material Type	Tested Packaged Device
Life Cycle Description (code)	REMOVED FROM ACTIVE PORTFOLIO
Status	No Longer Manufactured
Application/Qualification Tier	10-YEARS APPLICATION LIFE

Package Information

Parameter	Value
Package Description and Mechanical Drawing	QFP 160 28*28*3.3P0.65
Device Weight(g)	5.63505
Package Material	Plastic
Mounting Style	Surface Mount
Package Length (nominal)(mm)	28.000
Package Width (nominal)(mm)	28.000
Package Thickness (nominal)(mm)	3.400
Tape & Reel	No

Environmental and Compliance Information

Parameter	Value
Pb-Free	No
RoHS Compliant	No
Material Composition Declaration (MCD)	Download MCD Report  Download MCD Report 
RoHS Certificate of Analysis (CoA)	Contact Us
Moisture Sensitivity Level (MSL)	3
Floor Life	168 HOURS
Peak Package Body Temperature (PPT)(°C)	220
Maximum Time at Peak Temperature (s)	30
Number of Reflow Cycles	3
REACH SVHC	Freescle REACH Statement
UL94 (plastics flammability test)	V0: Burning stops within 10 seconds on a vertical specimen; no drips allowed

Manufacturing Information

Parameter	Value
Micron Size(?m)	.8

Ordering Information

Parameter	Value
Last Order Date	15 Sep 2006
Last Ship Date	16 Mar 2007
Exempt from Minimum Delivery Value	Yes
Export Control Classification Number (US)	EAR99
Harmonized Tariff (US) Disclaimer	8542.31.0000
CCATS Document	-
ENC Status	-
Other Trade Compliance Documents	-
Budgetary Price excluding tax(US\$) Change Currency	-
Order	Distributor

Product/Process Change Notice (PCN)

Number	Type	Title	Issue Date	Effectivity Date
11962	Product Discontinuance	TSPG MCD32 EOL 68HC16Y1 AND 68HC916R4	16 Mar 2006	16 Mar 2006
11712	Device Migration	TSPG MCD ROHS COMPLIANT NON-EXEMPT - 1	28 Dec 2005	28 Dec 2005
11462	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	14 Oct 2005	15 Oct 2005
11431	Product Bulletin	TSPG MCD ROHS COMPLIANT DEVICE MIGRATION	04 Oct 2005	05 Oct 2005
10742	Product Bulletin	KLM PACKING CHANGE FOR TRAY DEVICES	28 Mar 2005	02 Apr 2005
9048	Product Bulletin	TIC SUPPORT FOR QUALITY QUERIES IN EMEA	04 Aug 2003	05 Aug 2003
8023	Product Bulletin	160 MCR ASSY MOVE FROM SDI TO KLM	16 Sep 2002	17 Sep 2002
7278	Product Change Notice	FINAL MANUFACTURING ASSY CONSOLIDATIONS	28 Mar 2002	07 Jul 2002
7286	Product Bulletin	FINAL MANUFACTURING TEST CONSOLIDATIONS	28 Mar 2002	29 Mar 2002
6465	Product Bulletin	QFP160-28X28 TRAY CHANGE	30 May 2001	31 May 2001
5412	Product Bulletin	BURN-IN PROCESS FROM SENDAI TO KEDC	22 Feb 2000	23 Feb 2000
4967	Update Notification	UPDATE NOTICE TO PB4659: XQFP SHIPPING TRAY STANDARDIZATION (2 OF 4)	17 Aug 1999	18 Aug 1999
4659	Product Bulletin	XQFP SHIPPING TRAY STANDARDIZATION (2 OF 4)	15 Jun 1999	16 Jun 1999
4211	Product Bulletin	PACKING MATERIAL/METHOD CHANGE	29 Oct 1998	30 Oct 1998
3787	Product Bulletin	ADDITION OF SOLDER PLATING BATH SOLUTION	28 Aug 1998	05 Aug 1998

Operating Characteristics

Parameter	Value
Ambient Operating Temperature (Min-Max) (°C)	-40 to 85
Bus Frequency (Max) (MHz)	16
GPIOs	24
Internal RAM (KB)	2
Sample Exception Availability	N
Serial Interface - Number of Serial Interfaces	2
Serial Interface - Serial Interface Type	SPI
Timer Features	TPU
Timers - Timer Channels	8
Timers - Timer Size (bit)	16

[Reliability Data Lookup](#)